

# CRS06

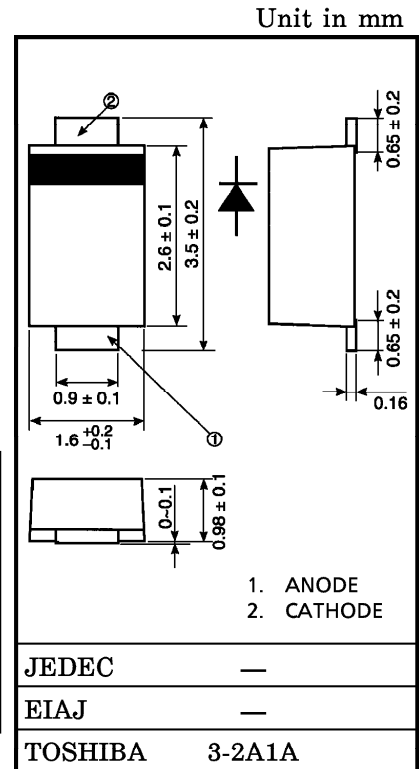
SWITCHING TYPE POWER SUPPLY APPLICATIONS

PORTABLE EQUIPMENT BATTERY APPLICATIONS

- Forward Voltage :  $V_{FM} = 0.36 \text{ V (Max.)}$
- Average Forward Current :  $I_{F(AV)} = 1.0 \text{ A}$
- Repetitive Peak Reverse Voltage :  $V_{RRM} = 20 \text{ V}$
- Small Package : S-FLAT™ (Toshiba designation)

**MAXIMUM RATINGS**

CHARACTERISTIC	SYMBOL	RATING	UNIT
Repetitive Peak Reverse Voltage	$V_{RRM}$	20	V
Average Forward Current	$I_O$	1.0	A
Peak One Cycle Surge Forward Current (Non-Repetitive)	$I_{FSM}$	20 (50 Hz)	A
Junction Temperature	$T_j$	-40~125	°C
Storage Temperature Range	$T_{stg}$	-40~125	°C



Weight : 0.013 g

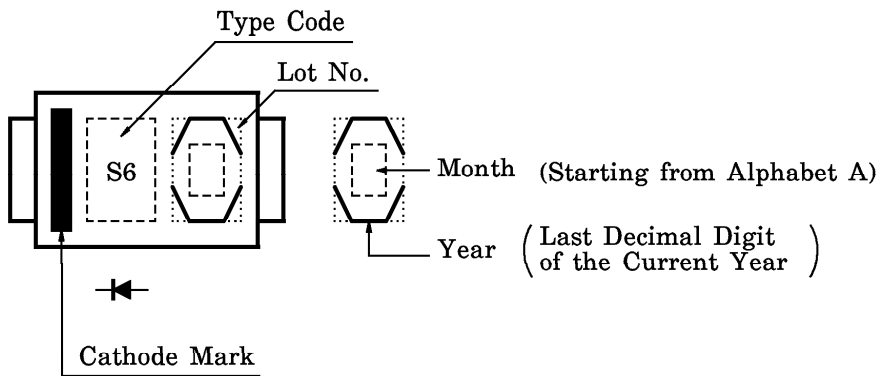
**ELECTRICAL CHARACTERISTICS (Ta = 25°C)**

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Peak Forward Voltage	$V_{FM(1)}$	$I_{FM} = 0.1 \text{ A}$	—	0.20	—	V
	$V_{FM(2)}$	$I_{FM} = 0.7 \text{ A}$	—	0.30	—	V
	$V_{FM(3)}$	$I_{FM} = 1.0 \text{ A}$	—	0.32	0.36	V
Repetitive Peak Reverse Current	$I_{RRM(1)}$	$V_{RRM} = 5 \text{ V}$	—	0.06	—	mA
	$I_{RRM(2)}$	$V_{RRM} = 20 \text{ V}$	—	—	1.0	mA
Junction Capacitance	$C_j$	$V_R = 10 \text{ V}, f = 1.0 \text{ MHz}$	—	60	—	pF
Thermal Resistance	$R_{th(j-a)}$	On ceramic substrate (Soldering Land 2 mm × 2 mm)	—	—	70	°C/W
		On glass-epoxy substrate (Soldering Land 2 mm × 2 mm)	—	—	140	°C/W

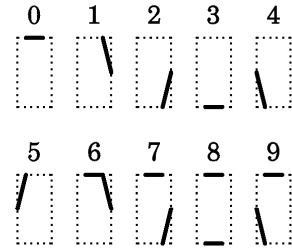
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**MARKING**



**FOLLOWING INDICATES THE DATE OF MANUFACTURE**



**STANDARD SOLDERING PAD**

Unit : mm

